DECEMBER 1983-REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

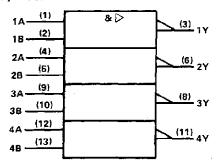
These devices contain four independent 2-input NAND buffer gates.

The SN5437, SN54LS37 and SN54S37 are characterized for operation over the full military range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN7437, SN74LS37 and SN74S37 are characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
<u>A</u> _	В	Y
Н	Н	L
L	×	н
X	L	Н

logic symbol†



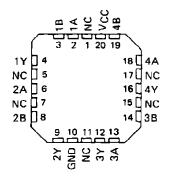
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN5437, SN54LS37, SN54S37... J OR W PACKAGE SN7437... N PACKAGE SN74LS37, SN74S37... D OR N PACKAGE (TOP VIEW)

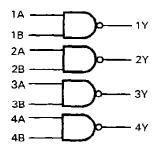
1A C 1B C 1Y C 2A C 2B C 2Y C	1 2 3 4 5	14 VCC 13 48 12 4A 11 4Y 10 3B 9 3A
2Y 🛚	6	9∐3A
GND 🗆	7	8 ☐ 3 Y

SN54LS37, SN54S37...FK PACKAGE (TOP VIEW)



NC - No internal connection

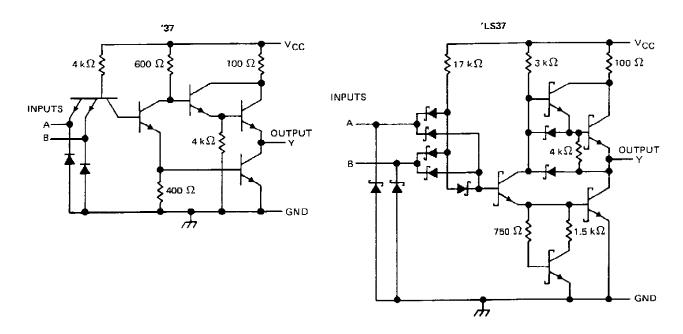
logic diagram

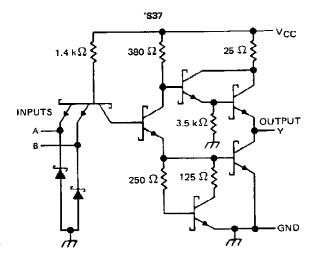


positive logic

 $Y = \overline{A \cdot B} \text{ or } Y = \overline{A} + \overline{B}$

schematics (each gate)





Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note	1)	
Input voltage: '37, 'S37		5.5 V
'LS37	,	7 V
Operating free-air temperature:	\$N54'	. –55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		. -65° C to 150° C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN5437	,		SN7437	•	UNIT
		MIN	NOM	MAX	MIN	MOM	MAX	CNII
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage		-	8.0			8.0	V
¹ ОН	High-level output current			- 1.2			- 1.2	mΑ
loL	Low-level output current			48			48	mΑ
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAGAMETER		TEST CONDIT	CONE †		SN5437			SN7437	,	
PARAMETER		LEST COMPLI	IUI45 I	MIN	TYP#	MAX	MIN	TYP#	MAX	UNIT
V _{IK}	V _{CC} ≈ MIN,	I _I = - 12 mA				- 1.5			- 1.5	V
v _{он}	V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = - 1.2 mA	2.4	3.3		2.4	3.3		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 48 mA		0.2	0.4		0.2	0.4	V
I ₁	V _{CC} = MAX,	V ₁ = 6.5 V				1			1	mA
ΊΗ	V _{CC} = MAX,	V = 2.4 V			-	40			40	μА
ΊΙĻ	VCC = MAX,	V _I = 0.4 V				- 1.6	T		- 1.6	mA
los§	V _{CC} = MAX			- 20		- 70	- 18		- 70	mA
Гссн	V _{CC} ≈ MAX,	V ₁ = 0 V			9	15.5		9	15.5	mΑ
ICCL	V _{CC} = MAX,	V ₁ = 4.5 V			34	54		34	54	mΑ

- † For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
- ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_{\Delta} = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
tPLH	A or B	×	$R_1 = 133 \Omega$,	C: - 45 p.F		13	22	กร
†PHL	Aora	,	nL - 133 12,	CL = 45 pF		8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN54LS37, SN74LS37 QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS

recommended operating conditions

		S	SN54LS37			SN74LS37			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			$\overline{}$	
VIL	Low-level input voltage			0.7			8.0	V	
Гон	High-level output current			-1.2			-1.2	mA	
loL	Low-level output current			12		-	24	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT	IONS T	8	N54LS	37	s	N74LS	37	UNIT
FARAIVIETER		TEST COMBIT	TONS 1	MIN		MAX	MIN	TYP#	MAX	UNIT
٧ _{IK}	VCC = MIN,	i _I = -18 mA				- 1.5			- 1.5	V
V _{OH}	VCC = MIN,	V _{IL} = MAX,	lон = — 1.2 mA	2.5	3.4		2.7	3.4	_	V
٧	VCC = MIN,	V _{IH} = 2 V,	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
V _{OL}	VCC = MIN.	V _{JH} = 2 V	10L = 24 mA					0.35	0.5	·
<u> 11</u>	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
ЧH	VCC = MAX,	V _I = 2.7 V	<u> </u>			20		_	20	μΑ
ΙĮĽ	V _{CC} = MAX,	V _I = 0.4 V		_		- 0.4			- 0.4	mA
IOS §	V _{CC} = MAX			- 30		130	- 30		- 130	mA
Іссн_	VCC = MAX,	V ₁ = 0 V			0.9	2		0.9	2	mA
ICCL	V _{CC} = MAX,	V _I = 4.5 V			6	12		6	12	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
₹PLH	A or B	~	$R_1 = 667 \Omega$,	C. = 45 nE		12	24	ns
tPH∟	40.6		R _L = 667 Ω,	C _L = 45 pF		12	24	กร

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

	-	SN54S3	7		SN74S3	7	
	MIN	NOM	MAX	MIN	MOM	MAX	UNIT
VCC Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH High-level input voltage	2			2			V
VIL Low-level input voltage			8.0			8.0	٧
IOH High-level output current			– 3			- 3	mA
IOL Low-level output current			60			60	mA
TA Operating free-air temperature	-55		125	0		70	ас

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				•						
		TEST CONDIT	uana t		SN54S3	7		7	UNIT	
PARAMETER		1E21 CONDIT	IONS 1	MIN	TYP ‡	MAX	MIN	TYP ‡	MAX	UNII
VIK	VCC = MIN,	I ₁ = - 18 mA			•	- 1.2			- 1.2	٧
Voн	V _{CC} = MIN,	V _{IL} = 0.8 V,	l _{OH} = - 3 mA	2.5	3.4		2.7	3.4		
VoL	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 60 mA			0.5			0.5	V
tı	VCC = MAX,	V _I = 5.5 V				1			1	mA
Iн	V _{CC} = MAX,	V ₁ = 2.7 V				0.1			0.1	mA
IIL I	V _{CC} = MAX,	V _I = 0.5 V			-	-4			- 4	mA
I _{OS} §	V _{CC} = MAX			50		- 225	- 50		- 225	mA
Гссн	V _{CC} = MAX,	V ₁ - 0 V	•		20	36		20	36	mA
CCL	V _{CC} = MAX,	V _I = 4.5		<u>-</u>	46	80		46	80	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed 100 milliseconds.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM	TO	TEST CONDITIONS		MIN TYP	MAX	UNIT
	(INPUT)	(OUTPUT)					
tPLH			P 02 O	C: = 50 nE	4	6.5	ns
tPHL	A or B		$R_L = 93 \Omega$, $C_L = 50 pF$	OF . 20 by	4	6.5	ns
[†] PLH	A OF B	· . [R _L = 93 Ω,	C ₁ = 150 pF	6		กร
t _{PHL}			a2 25'		6		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9754101Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9754101QCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9754101QCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9754101QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
5962-9754101QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5437J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN5437J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS37J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS37J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S37J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S37J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7437N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7437N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7437N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7437N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS37D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS37D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS37N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS37N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS37N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS37N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS37NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS37NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS37NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS37NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS37NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS37NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
 SN74S37DR	ACTIVE	SOIC	D	14	2500	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM





6-Dec-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
SN74S37DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S37N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S37N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S37N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S37NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S37NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S37NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S37NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ5437J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5437J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5437W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ5437W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54LS37FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS37FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS37J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS37J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS37W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS37W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S37FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S37FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S37J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S37J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S37W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S37W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect. **NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check



PACKAGE OPTION ADDENDUM

6-Dec-2006

http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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